

In the Specification

As a new paragraph before "BACKGROUND OF THE INVENTION" on page 1, line 3, please insert the following:

Cross-Reference to Related Applications

This application is a continuation application of copending, commonly assigned Application No. 09/606,825, filed June 28, 2000, the disclosure of which is incorporated herein by reference.

Please replace the paragraph beginning at page 1, line 28 by the following paragraph.

Metal foils having microrough surfaces can give excellent results when used as electrodes in contact with conductive polymers. U.S. Patent No. 4,689,475 discloses the use of metal foils that have surface irregularities, e.g. nodules, which protrude from the surface by 0.1 to 100 μm and have at least one dimension parallel to the surface which is at most 100 μm . U.S. Patent No. 4,800,253 discloses the use of metal foils with a microrough surface which comprises macronodules which themselves comprise micronodules. U.S. Patent No. 5,874,885 discloses the use of a metal electrode made of more than one type of metal with particular surface characteristics. Other documents which disclose the use of metal foils having rough surfaces, but which do not disclose the characteristics of the foils, are Japanese Patent Kokai No. 62-113402 (Murata, 1987), Japanese Patent Kokoku H4-18681 (Idemitsu Kosan, 1992), and German Patent Application No. 3707494A (Nippon Mektron Ltd., 1988). U.S. Patent No. 5,880,668 discloses the use of a modified polyolefin with a carboxylic acid derivative grafted onto the polymer in combination with certain foils. The disclosure of each of these documents is incorporated herein by reference.

Please replace the paragraph beginning at page 3, line 20 by the following paragraph.

Additionally, an adhesion promoting layer such as a coupling agent can be used between the foil and the conductive element. The use of adhesion promoting layers in combination with foils having certain roughness characteristics is described in copending commonly assigned Application No. 09/606,821 (Becker et al.), filed contemporaneously with this application, the disclosure of which is incorporated herein by reference.